

## LMX2604

## Triple-band VCO for GSM900/DCS1800/PCS1900

## **General Description**

The LMX2604 is a fully integrated VCO (Voltage-Controlled Oscillator) IC designed for GSM900/DCS1800/PCS1900 triple-band application. The IC is ideal for use in the transmitter modulation loop by providing extremely small form factor and low phase noise. The IC has two VCOs, one for GSM and a second for DCS/PCS. The IC has two separate buffer amplifiers to drive an external high power amplifier, one for GSM900 band and the other one for DCS1800/PCS1900 bands. The IC also has a differential buffer amplifier to drive a mixer for the offset PLL.

The resonant circuits of the VCOs are fully integrated in the chip to ease the application of the IC. The high quality factor of the embedded tank circuit achieves very low phase noise characteristics at the VCO output. The only required external components are a couple of supply bypass capacitors and matching components.

A control pin for controlling the oscillation frequency is shared by the two VCOs.

The LMX2604 IC is provided in a 20-pin 4x4 LLP (Leadless Leadframe package).

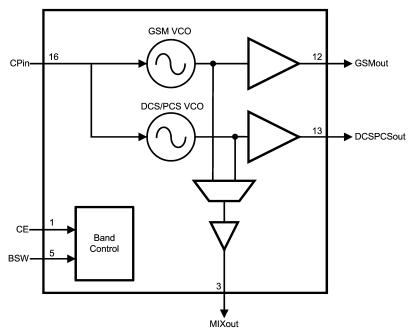
#### **Features**

- On-chip Triple-band RF VCOs GSM: 880 MHz to 915 MHz DCS: 1710 MHz to 1785 MHz PCS: 1850 MHz to 1910 MHz
- On-chip tank circuit
- Low phase noise
  - -- -167 dBc/Hz @ 20 MHz offset in GSM band
  - -163 dBc/Hz @ 20 MHz offset in DCS band
  - -162 dBc/Hz @ 20 MHz offset in PCS band
- High output power
  - +6 dBm in GSM mode
  - -+6 dBm in DCS and PCS mode
- Low current consumption
  - 18 mA in GSM mode
  - 15 mA in DCS and PCS mode
- +2.6 V to +3.0 V supply voltage
- 0.25 µm RF CMOS process
- Small 20-pin 4x4 LLP package

### **Applications**

- Transmit VCO for GSM, DCS, and PCS
- Closed loop modulation systems

## **Functional Block Diagram**

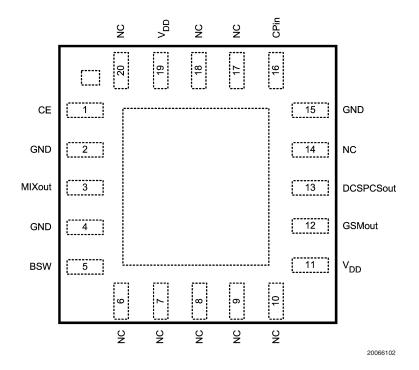


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# **Connection Diagram**

### 20-Pin 4x4 LLP (TM) Package



# **Pin Descriptions**

Pin Number	Name	I/O	Description
1	CE	ı	Chip enable input pin. High=enable, Low=disable
2,4,15	GND (Note 1)	_	Ground pins
3	MIXout	0	Mixer output pin (RF output)
5	BSW	I	Band switch input pin. High=DCS/PCS, Low=GSM
11,19	VDD	_	Supply voltage pins
12	GSMout	0	RF output pin for VCO in GSM band
13	DCSPCSout	0	RF output pin for VCO in DCS and PCS band
16	CPin	I	Charge pump input pin
6,7,8,9,10,14,17,18,20	NC	_	No Connection, These pins must be left open

Note 1: The exposed die attach pad is grounded.

## **Ordering Information**

Package	Part Number	Package Marking	Media Transport	NSC Drawing
20-Pin LLP	LMX2604LQ	LMX2604LQ	1000 Unit Tape and Reel	LQA20A
20-Pin LLP	LMX2604LQX	LMX2604LQ	4500 Unit Tape and Reel	LQA20A

## Absolute Maximum Ratings (Notes 3, 4, 5)

Parameter	Symbol	Ratings	Unit
Supply Voltage	V <sub>DD</sub>	-0.3 to 3.6	V
Input Voltage	V <sub>IN</sub>	-0.3 to V <sub>DD</sub> +0.3	V
Input Current (Note 2)	I <sub>IN</sub>	10	mA
Storage Temperature Range	T <sub>STG</sub>	-65 to 150	°C

Note 2: Maximum input current is for a logic pin, not the power pins.

## **Recommended Operating Conditions**

Parameter	Symbol	Condition	Min	Typical	Max	Unit
Ambient Temperature	T <sub>A</sub>	V <sub>DD</sub> =3V	-30	25	85	°C
Supply Voltage (to GND)	$V_{DD}$		2.6	2.8	3.0	V

**Note 3:** "Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but do not guarantee specific performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed.

Note 4: This Device is a high performance RF integrated circuit with an ESD rating < 2 kV and is ESD sensitive. Handling and assembly of this device should only be done at ESD-free workstations.

**Note 5:** Stresses in excess of the absolute maximum ratings can cause permanent or latent damage to the device. These are absolute stress ratings only. Functional operation of the device is only implied at these or any other conditions in excess of those given in the operation sections of the data sheet. Exposure to absolute maximum ratings for extended periods can adversely affect device reliability

### **Electrical Characteristics**

AC Characteristics (V<sub>DD</sub>=2.8V, T<sub>A</sub>=25°C; unless otherwise noted)

Symbol	Parameter	Remarks	Min	Тур	Max	Units	
		GSM Band	880		915	MHz	
f	Frequency Range	DCS Band	1710		1785	MHz	
		PCS Band	1850		1910	IVITZ	
	Tuning Sensitivity (Note 6)	GSM Band	10	15	20		
$K_{VCO}$		DCS Band	15	20	25	MHz/V	
	(Note o)	PCS Band	20	25	30		
Pout	Output Dower	GSM Band	4	6	8	dBm	
Poul	Output Power	DCS & PCS Band	4	6	8	ubiii	
PMIXout	Output power of	GSM Band	-5.5	-3.5	-1.5	dBm	
PIVIIAOUL	MIXout pin	DCS & PCS Band	-4.5	-2.5	-0.5	UDIII	
	L(f) Phase Noise (GSM Band)	at 100 kHz offset		-120		dBc/Hz	
I (f)		at 400 kHz offset		-136	-128		
L(I)		at 3 MHz offset (Note 7)		-152			
		at 20 MHz offset (Note 7)		-167			
		at 100 kHz offset		-112			
I ( <b>f</b> )	Phase Noise	at 400 kHz offset		-130	-124	dBc/Hz	
L(f)	(DCS Band)	at 3 MHz offset (Note 7)		-146		UDC/FIZ	
		at 20 MHz offset (Note 7)		-163			
		at 100 kHz offset		-110			
Phase Noise	Phase Noise	at 400 kHz offset		-129	-124	dBc/Hz	
L(f)	(PCS Band)	at 3 MHz offset (Note 7)		-145		ubc/r12	
		at 20 MHz offset (Note 7)		-162			
	Second Harmonic Suppression	All Bands at RF output port.		-20	-15	dBc	

Note 6: Tuning Sensitivty is measured after coarse lock. Minimum and maximum limits are supported by characterization.

Note 7: Supported by characterization

## **Electrical Characteristics** (Continued)

DC Characteristics ( $V_{DD}$ =2.8V,  $T_A$ =25°C; unless otherwise noted)

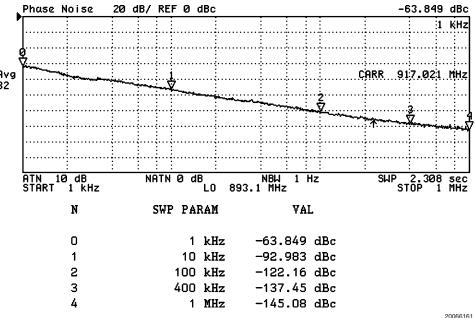
Symbol	Parameter	Condition	Min	Тур	Max	Units
V <sub>IH</sub>	Logical Input High Voltage		0.8V <sub>DD</sub>		V <sub>DD</sub> +0.3	V
$V_{IL}$	Logical Input Low Voltage		-0.3		0.2V <sub>DD</sub>	V
I <sub>IH</sub>	Logical Input High Current		-2.5		2.5	μΑ
$I_{\rm IL}$	Logical Input Low Current		-2.5		2.5	μА
	Input Capacitance			5		pF
I <sub>DD,GSM</sub>	Supply Current (Note 8)			18	21	mA
I <sub>DD,DCS/PCS</sub>	Supply Current (Note 8)			15	18	mA
I <sub>std</sub>	Standby Current				2.5	μA

Note 8: The current consumption in VCO and driver amplifier is all included

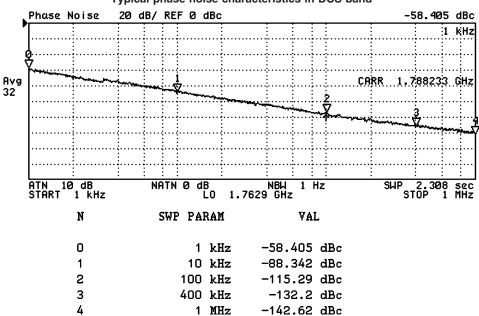
Note 9: For CE, BSW, and CPin pins

## **Typical Performance Characteristics: Phase Noise**

### Typical phase noise characteristics in GSM band

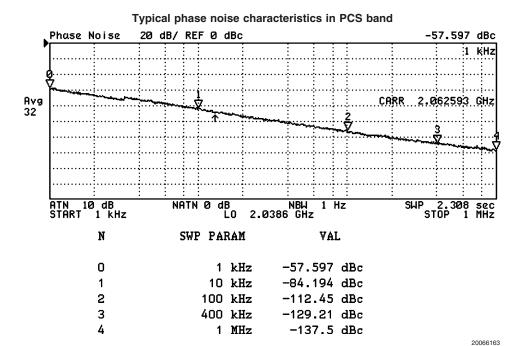


#### Typical phase noise characteristics in DCS band

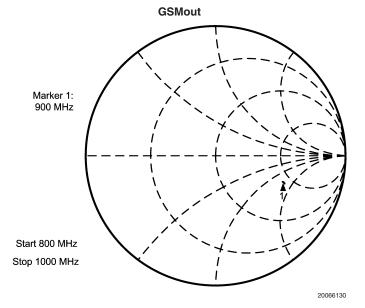


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# Typical Performance Characteristics: Phase Noise (Continued)

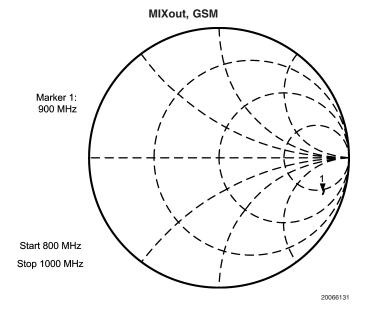


# **Typical Performance Characteristic: GSMout Impedance**



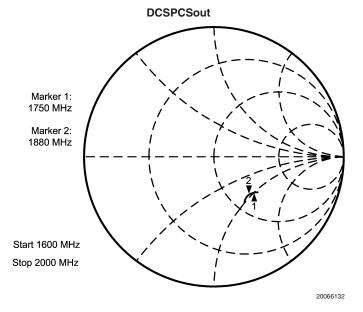
GSMout				
Frequency (MHz)	Real (Ohms)	Imaginary (Ohms)	Absolute (Ohms)	
800	126	-72	146	
850	126	-74	146	
900	126	-75	146	
950	126	-77	147	
1000	125	-80	149	

# Typical Performance Characteristic : MIXout Impedance, GSM



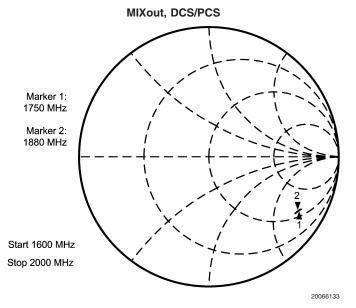
	MIXout, GSM				
Frequency (MHz)	Real (Ohms)	Imaginary (Ohms)	Absolute (Ohms)		
800	141	-256	292		
850	133	-249	282		
900	126	-243	274		
950	120	-237	266		
1000	115	-232	259		

# **Typical Performance Characteristic: DCSPCSout Impedance**



DCSPCSout				
Frequency (MHz)	Real (Ohms)	Imaginary (Ohms)	Absolute (Ohms)	
1600	80	-54	96	
1650	78	-53	94	
1700	77	-51	93	
1750	76	-50	91	
1800	73	-49	88	
1850	71	-48	85	
1900	68	-48	83	
1950	64	-48	80	
2000	57	-51	77	

# Typical Performance Characteristic : MIXout Impedance, DCS/PCS



MIXout, DCSPCS				
Frequency (MHz)	Real (Ohms)	Imaginary (Ohms)	Absolute (Ohms)	
1600	66	-164	177	
1650	65	-162	175	
1700	64	-160	172	
1750	66	-157	171	
1800	64	-157	169	
1850	63	-153	166	
1900	62	-150	162	
1950	61	-146	159	
2000	59	-143	155	

## **Functional Description**

#### PRODUCT DESCRIPTION

The LMX2604 IC has two VCOs, which are configured as an LC resonant oscillator. The active components and tank elements are all integrated on the IC. The oscillator core and the tank circuit are designed to be immune to external noise such as supply and load variation. The IC is easy-to-use and occupies extremely small area in the board.

Two output amplifiers are also integrated to deliver high output power of +6 dBm in GSM/DCS/PCS applications. The amplifiers isolate the oscillator cores from the external load, and drive the external 50 ohm load. The output driver is designed to have low noise floor and to reduce pulling by load variation. An additional amplifier to drive the mixer in the transmit PLL is also provided. Only an attenuator composed of a few passive elements is necessary to meet the power level of the mixer input of the transmit PLL.

The frequency of the oscillator is controlled by the CPin pin, which is internally connected to the varactor. This control pin is connected to the loop filter of the modulation loop in the transmit path. Any additional noise on this tuning input is directly translated into FM noise, which can degrade the phase noise characteristics of the oscillator. Typically, the loop filter of the PLL provides an appropriately low impedance source at its output and thus proper additional filtering stage is often required to reduce the high frequency noise and spurious signals.

# FREQUENCY SELECTION AND POWER DOWN CONTROL

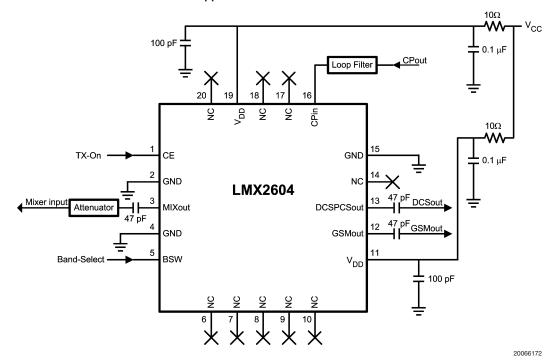
The BSW pin selects the operating frequency band. The table below shows the appropriate settings with the CE pin.

CE	BSW	Output
Low	Low	X
Low	High	X
High	Low	Low Band (GSM)
High	High	High Band (DCS/PCS)

In real implementation, the component values of the tank circuit vary from the nominal value. The IC has built-in circuit to track the variation and compensate that kind of the variation during normal operation. This self-correction algorithm does not require any external control signal and elements. The figure below shows an application circuit of the LMX2604. The LMX2604 is developed for the use in a GSM handset as part of the transmitter PLL. To complete the offset PLL in the transmit path, several passive elements for the external loop filter should be also provided. The charge pump output port of the external transceiver IC is fed to the CPin pin.

The locking process of the LMX2604 is composed of two stages. First, the internal control circuitry of the LMX2604 controls the fast frequency acquisition behavior of the LMX2604. After the frequency acquisition, the whole loop enters in its normal operating mode.

#### **Application Circuit of LMX2604**



## Functional Description (Continued)

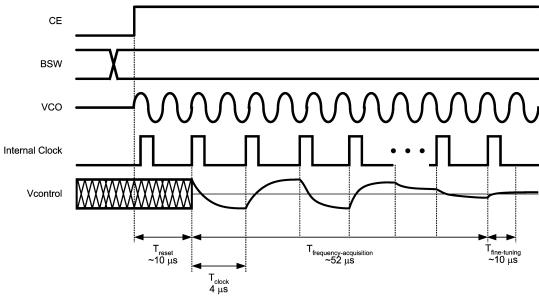
#### FREQUENCY ACQUISITION

On the rising edge of CE the VCO goes through a frequency acquisition mode which coarse locks the PLL to the approximate final frequency. This portion of the lock digitally sets the

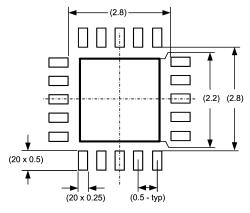
frequency such that the final tuning voltage on the CPin line of the VCO is approximately Vdd/2. Benefits of this system is the maximum required charge pump voltage is reduced as large frequency ranges may be tuned with a small tuning voltage. This makes the digitally tuned VCO different from conventional analog VCOs.

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### Frequency Acquisition Timing Diagram

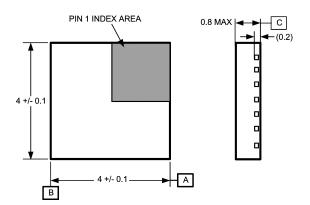


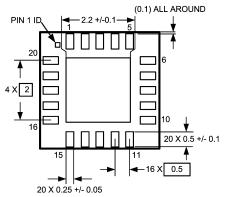
## Physical Dimensions inches (millimeters) unless otherwise noted



#### RECOMMENDED LAND PATTERN

1:1 RATIO WITH PKG SOLDER PADS





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20-Pin LLP (Leadless Leadframe package) Package Order Number LMX2604LQX for 4500 Unit Reel Order Number LMX2604LQ for 1000 Unit Reel NS Package Number LQA20

### **Notes**

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